

### 20mm BIG LAMP

Part Number: DLC/6EGW

High Efficiency Red

#### **Features**

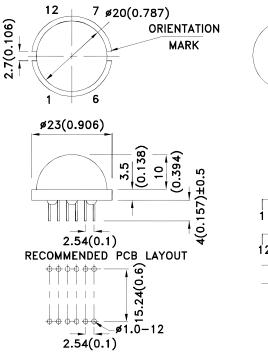
- 12 pins.
- High luminous intensity.
- Low power consumption.
- Wide viewing angle.
- Categorized for luminous intensity.
- Excellent on / off contrast.
- Easy mounting on P.C. board or sockets.
- Solid state reliability.
- RoHS compliant.

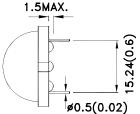
### Description

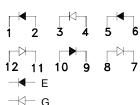
The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

# **Package Dimensions**







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SPEC NO: DSAD3972 **REV NO: V.5** DATE: MAR/19/2011 **PAGE: 1 OF 7** APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: C.H.Han ERP: 1338000034

### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
DLC/6EGW	High Efficiency Red (GaAsP/GaP)	White Diffused	15	32	- 120°
	Green (GaP)	White Dillused	15	26	

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

# Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	IF=20mA	
λD [1]	Dominant Wavelength	High Efficiency Red Green	625 568		nm	IF=20mA	
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	IF=20mA	
С	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	IF=20mA	
lR	Reverse Current	High Efficiency Red Green		10 10	uA	V <sub>R</sub> = 5V	

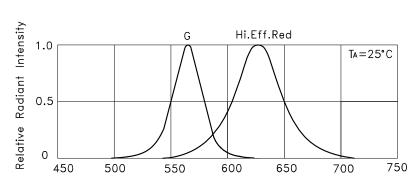
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

# Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage	· ·	V			
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				

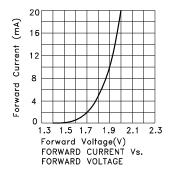
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
   2. 2mm below package base.

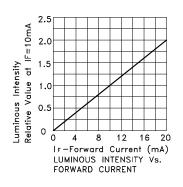
SPEC NO: DSAD3972 **REV NO: V.5** DATE: MAR/19/2011 PAGE: 2 OF 7 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: C.H.Han ERP: 1338000034

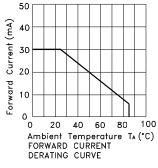


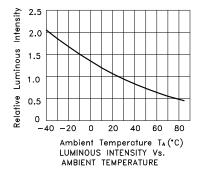
wavelength  $\times$  (nm) RELATIVE INTENSITY Vs. WAVELENGTH

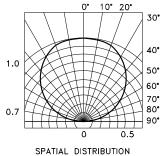
# DLC/6EGW High Efficiency Red







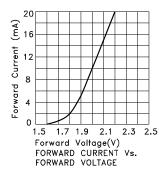


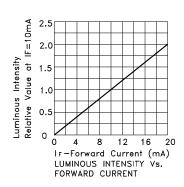


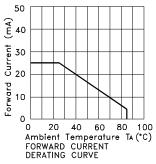
 SPEC NO: DSAD3972
 REV NO: V.5
 DATE: MAR/19/2011
 PAGE: 3 OF 7

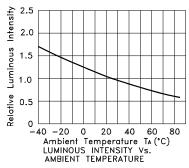
 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: C.H.Han
 ERP: 1338000034

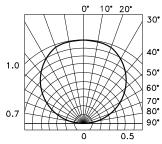
### Green







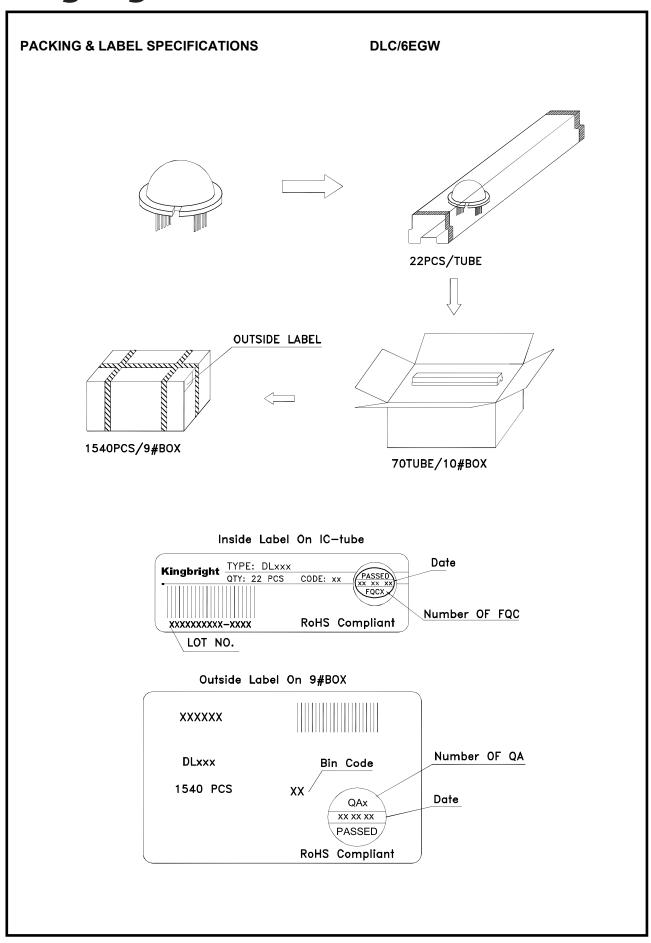




SPATIAL DISTRIBUTION

 SPEC NO: DSAD3972
 REV NO: V.5
 DATE: MAR/19/2011
 PAGE: 4 OF 7

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: C.H.Han
 ERP: 1338000034

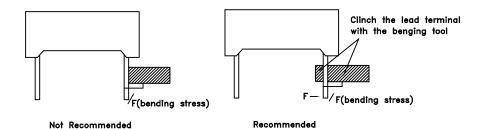


SPEC NO: DSAD3972 APPROVED: WYNEC REV NO: V.5 CHECKED: Allen Liu DATE: MAR/19/2011 DRAWN: C.H.Han PAGE: 5 OF 7 ERP: 1338000034

### THROUGH HOLE DISPLAY MOUNTING METHOD

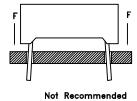
# Lead Forming

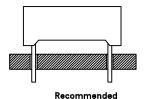
Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.



# Installation

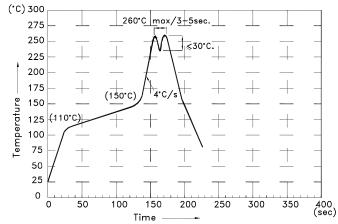
- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.





#### DISPLAY SOLDERING CONDITIONS

Wave Soldering Profile For Lead-free Through-hole LED.



# NOTES:

- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C 5.No more than once.

 SPEC NO: DSAD3972
 REV NO: V.5
 DATE: MAR/19/2011
 PAGE: 6 OF 7

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: C.H.Han
 ERP: 1338000034

# Soldering General Notes:

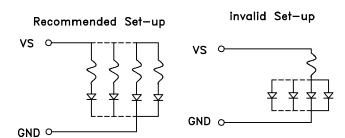
- a. Through—hole displays are incompatible with reflow soldering.
- b. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

### **CLEANING**

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- 2. If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

### CIRCUIT DESIGN NOTES

- 1.Protective current-limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



PAGE: 7 OF 7

ERP: 1338000034

SPEC NO: DSAD3972 REV NO: V.5 DATE: MAR/19/2011
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: C.H.Han